



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-03-10
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration * Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99DZ100GPTR	NF9J*UBF9ABP	A	959	2022-03-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	260	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00813279	

Package Designator	Package Size	Nbr of instances	Shape	
QFP	10.00,10.00,1.40	64	gull wing	
Comment	LQFP 64 10x10x1.4 1.0 ExPad Down. MDF valid for CPs: L99DZ100GP,L99DZ100GPTR			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption id.	Description

QueryList : California Prop65 list, dated 17th Dec 2021			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			true
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.203	die	781

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GB 26572 – 2014				
Query				Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products				false
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products				false
Hasardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-17 Jan 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Cobalt, Gold, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	NF91*UBF9ABP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	21.553	mg	supplier	die	Silicon(Si)	7440-21-3		19.412	mg	900664	74662
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.046	mg	2134	177
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.011	mg	510	42
				supplier	metallisation	Copper(Cu)	7440-50-8		1.202	mg	55769	4623
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.002	mg	93	8
				supplier	metallisation	Gold(Au)	7440-57-5		0.030	mg	1392	115
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.203	mg	9419	781
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.047	mg	2181	181
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.008	mg	371	31
				supplier	metallisation	Tungsten(W)	7440-33-7		0.068	mg	3155	262
				supplier	metallisation	Vanadium(V)	7440-62-2		0.003	mg	139	12
				supplier	passivation	Silicon oxide	7631-86-9		0.298	mg	13826	1146
				supplier	polymer coating	polyimide	proprietary		0.223	mg	10347	858
				Leadframe	M-004 Copper and its alloys	111.959	mg	supplier	alloy	Copper(Cu)	7440-50-8	
supplier	alloy	Iron(Fe)	7439-89-6						2.566	mg	22919	9869
supplier	alloy	Iron phosphide	1310-43-6						0.155	mg	1384	596
supplier	alloy	Zinc(Zn)	7440-66-6						0.134	mg	1197	515
Die attach	M-011 Other inorganic materials	2.491	mg	supplier	glue	Silver(Ag)	7440-22-4		2.221	mg	891610	8542
				supplier	glue	Isobornyl Methacrylate	7534-94-3		0.187	mg	75070	719
				supplier	glue	Bismaleimide resin	proprietary		0.075	mg	30108	288
				supplier	glue	Epoxy cyclohexylethyltrimethoxysilane	3388-04-3		0.008	mg	3212	31
				supplier	wire	Copper(Cu)	7440-50-8		2.840	mg	1000000	10923
Bonding wires	M-004 Copper and its alloys	2.840	mg	supplier	wire	Copper(Cu)	7440-50-8		2.888	mg	1000000	8031
Bonding wires 2	M-004 Copper and its alloys	2.088	mg	supplier	wire	Copper(Cu)	7440-50-8		94.078	mg	814499	361838
Encapsulation	M-011 Other inorganic materials	115.504	mg	supplier	mold compound	Silica vitreous	60676-86-0		8.663	mg	75002	33319
				supplier	mold compound	Silicon oxide	7631-86-9		8.663	mg	75002	33319
				supplier	mold compound	Epoxy type resin	proprietary		3.465	mg	29999	13327
				supplier	mold compound	Phenol type resin	proprietary		0.635	mg	5498	2442
				supplier	mold compound	Carbon black	1333-86-4		3.565	mg	1000000	13712
Connections coating	Solder	3.565	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		3.565	mg	1000000	13712